

<div><div><div>Telink</div></div></div>				<div>Telink Semiconductor (Shanghai) CO., LTD Phone: +8621 2028 1118 Fax: 8621 5038 8081 1500 Zuchongzhi Road Bldg 3 PuDong District, Shanghai, China 201203</div>					
Composition Table									
To:		TELINK SEMICONDUCTOR (SHANGHAI) CO., LTD.							
From:		Tongfu Microelectronics Co.,Ltd							
Product Name:		TLSR8258F512ET32							
Weight(Unit):		59.4456 mg					Date:		2024/6/25
	Material name	Vendor	Weight(mg)	Substance Name	CAS No	Weight(mg)	Content (%) Substance	Content (%) Whole chip	Content (ppm)
Die1	Telink Die	SMIC BJ	0.8000	Silicon	7440-21-3	0.8000	100.00%	1.35%	1000000
Die2	GD Die	SMIC BJ	0.2100	Silicon	7440-21-3	0.2100	100.00%	0.35%	1000000
Lead Frame	A194 F.H	AAMI	30.3100					50.70%	
				Cu	7440-50-8	29.5303	97.43%	49.68%	974275
				Fe	7439-89-6	0.7123	2.35%	1.20%	23500
				Pb	7439-92-1	0.0045	0.02%	0.01%	150
				P	7723-14-0	0.0250	0.08%	0.04%	825
				Zn	7440-66-6	0.0379	0.13%	0.06%	1250
DAF	HR-5104	RESONAC Materials	0.0256					0.02%	
				Epoxy resin A	Trade secret	0.0026	10.0%	0.00%	100000
				Epoxy resin B	Trade secret	0.0036	14.0%	0.01%	140000
				Phenol Resin	Trade secret	0.0036	14.0%	0.01%	140000
				SiO2 Filler	Trade secret	0.0123	48.0%	0.02%	480000
				Acrylic Copolymer	Trade secret	0.0036	14.0%	0.01%	140000
Epoxy	9246LB5	Yihua	0.1000					0.08%	
				Diethylene glycol monoethyl ether acetate	112-15-2	0.0100	10.00%	0.02%	100000
				Silica	15468-32-3	0.0600	60.00%	0.10%	600000
				Acylate resin	Proprietary	0.0150	15.00%	0.03%	150000
				Epoxy resin	Proprietary	0.0140	14.00%	0.02%	140000
				Peroxide	Proprietary	0.0010	1.00%	0.00%	10000
Wire	AGOF	PPM	0.3400					0.58%	
				Ag	7440-22-4	0.3332	98.0000%	0.56%	980000
				others	/	0.0068	2.0000%	0.01%	20000
Mold Compound	EME-G631BQ	RESONAC Materials	26.3900					45%	
				Epoxy ResinA	Trade secret	0.7917	3.00%	1.33%	30000
				Epoxy ResinB	Trade secret	0.7917	3.00%	1.33%	30000
				Phenol Resin	Trade secret	1.9793	7.50%	3.33%	75000
				Silica(Amorphous) A	60676-86-0	19.9113	75.45%	33.49%	754500
				Silica(Amorphous) B	7631-86-9	1.9793	7.50%	3.33%	75000
				Metal Hydroxide	Trade secret	0.7917	3.00%	1.33%	30000
				Carbon Black	1333-86-4	0.1451	0.55%	0.24%	5500
Plating	TIN	AISEN	1.2700					2.76%	
				Tin	7440-31-5	1.2699	99.99%	2.14%	999900
				Others	Trade Secret	0.0001	0.01%	0.00%	100
Total			59.4456			59.4456	100%	1000000	